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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Satoshi TAKANO

Application No.: 09/819,695



Docket No.: 109107

Filed: March 29, 2001

For: SEMICONDUCTOR MANUFACTURING METHOD, SUBSTRATE PROCESSING
METHOD, AND SEMICONDUCTOR MANUFACTURING APPARATUS

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REQUEST FOR CORRECTION OF PALM RECORDS

Director of the U.S. Patent and Trademark Office
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Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

James A. Oliff
Registration No. 27,075

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Date: July 30, 2001

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/819,690	03/29/2001	2812	1000	109107	7	8	5

CONFIRMATION NO. 3148

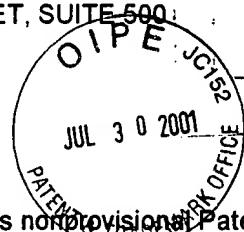
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UPDATED FILING RECEIPT


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Applicant(s)

Satoshi Takano, Tokyo, JAPAN;

NAKANO-KU

Domestic Priority data as claimed by applicant

Assignment for Published Patent Application

HITACHI KOKUSAI ELECTRIC INC.

Foreign Applications

JAPAN 2000-91642 03/29/2000

JAPAN 2001-60136 03/05/2001

If Required, Foreign Filing License Granted 05/05/2001

Projected Publication Date: 10/04/2001

No Publication Request: No

Early Publication Request: No

Title

Semiconductor manufacturing method, substrate processing method, and semiconductor manufacturing apparatus

Preliminary Class

438



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Bib Data Sheet

CONFIRMATION NO. 3148

SERIAL NUMBER 09/819,690	FILING DATE 03/29/2001 RULE	CLASS 438	GROUP ART UNIT 2812	ATTORNEY DOCKET NO. 109107	
APPLICANTS Satoshi Takano, Nakand-Ku, JAPAN;					
** CONTINUING DATA					
** FOREIGN APPLICATIONS					
JAPAN 2000-91642 03/29/2000 JAPAN 2001-60136 03/05/2001					
IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 05/05/2001					
Foreign Priority claimed 35 USC 119 (a-d) conditions met Verified and Acknowledged	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance Examiner's Signature Initials	STATE OR COUNTRY JAPAN	SHEETS DRAWING 7	TOTAL CLAIMS 8	INDEPENDENT CLAIMS 5
ADDRESS 25944 25944					
TITLE Semiconductor manufacturing method, substrate processing method, and semiconductor manufacturing apparatus					
FILING FEE RECEIVED 1000	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit			